

OC192-XFP-IR1-OPC

Brocade® (Formerly) OC192-XFP-IR1 Compatible TAA Compliant OC-192-I2 XFP Transceiver (SMF, 1310nm, 40km, LC, DOM)

Features

- INF-8077i Compliance
- Duplex LC Connector
- Single-mode Fiber
- Commercial Temperature 0 to 70 Celsius
- Hot Pluggable
- Metal with Lower EMI
- Excellent ESD Protection
- RoHS Compliant and Lead Free



Applications:

- OC-192 Transmission
- Access and Enterprise

Product Description

This Brocade® (Formerly) OC192-XFP-IR1 compatible XFP transceiver provides OC-192 (9953mbps) transmission rates for up to 40km over single-mode fiber (SMF) using a wavelength of 1310nm via an LC connector. It is guaranteed to be 100% compatible with the equivalent Brocade® (Formerly) transceiver. This easy to install, hot swappable transceiver has been programmed, uniquely serialized and data-traffic and application tested to ensure that it will initialize and perform identically. Digital optical monitoring (DOM) support is also present to allow access to real-time operating parameters. This transceiver is Trade Agreements Act (TAA) compliant. We stand behind the quality of our products and proudly offer a limited lifetime warranty.

Regulatory Compliance

- ESD to the Electrical PINs: compatible with MIL-STD-883E Method 3015.4
- ESD to the LC Receptacle: compatible with IEC 61000-4-3
- EMI/EMC compatible with FCC Part 15 Subpart B Rules, EN55022:2010
- Laser Eye Safety compatible with FDA 21CFR, EN60950-1& EN (IEC) 60825-1,2
- RoHS compliant with EU RoHS 2.0 directive 2015/863/EU

Absolute Maximum Ratings

Parameter	Symbol	Min.	Max.	Unit
Maximum Supply Voltage	V _{cc3}	-0.5	4.0	V
Storage Temperature	T _S	-40	85	°C
Operating Temperature	T _O	0	70	°C
Operating Humidity	RH	5	85	%
Receiver power	R _{MAX}		0.5	dBm
Maximum bitrate	B _{max}	9.95	11.3	Gbps

Electrical Characteristics (TOP=25°C, V_{cc}=3.3Volts)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Notes
Power Supply Voltage	V _{cc3}	3.14	3.30	3.46	V	
Power Supply Current	I _{cc3}			550	mA	
Power Dissipation	P _{DISS}			2	W	
Transmitter						
Differential data input swing	V _{in,pp}	180		700	mV	
Input differential impedance	Z _{in}		100		Ω	
Receiver						
Differential data output swing	V _{out, pp}	340	650	850	mV	
Output differential impedance	Z _o		100		Ω	

Optical Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Notes
Transmitter						
Launch Optical Power (average)	P _o	2		5	dBm	1
Optical Extinction Ratio	EX	3.5			dB	
Optical Wavelength	Tλ	1260	1310	1350	nm	
Transmitter and Dispersion Penalty	TDP			3.2	dB	
Average Optical Power (Laser Off)	P _{off}			-30	dBm	1
Receiver						
Receiver Sensitivity @10.3Gb/s	Rx _{sen}			-14.4	dBm	2
Receiver overload	P _{max}	0.5			dBm	3
Receiver wavelength	Rλ	1260		1600	nm	
Receiver Reflectance	TRrx			-16	dBm	

Notes:

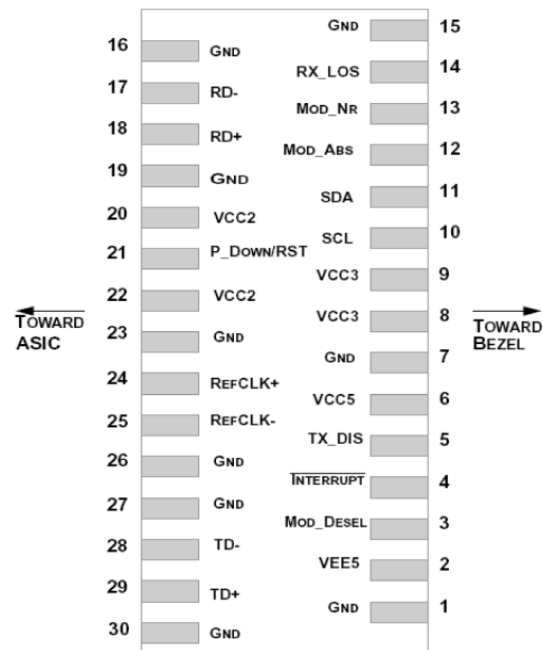
1. The optical power is launched into SMF.
2. Measured with worst ER: BER<10⁻¹²; 2³¹-1 PRBS
3. Exceeding the Receiver overload can physically damage the module. Please use appropriate attenuation.

Pin Descriptions

Pin	Symbol	Name/Descriptions	Ref.
1	GND	Module Ground	
2	Vee5	(not required)	
3	MOD_DESEL	Module De-select; When Held low allows the module to respond to 2-wire serial interface. LVTTTL-I	
4	/INTERRUPT	Interrupt; Indicates presence of an important condition which can be read via the 2-wire serial interface. LVTTTL-O	2
5	TX_DIS	Transmitter Disable. Logic1 indicates laser output disabled, LVTTTL-I	
6	VCC5	+5V Power Supply (Not required)	
7	GND	Module Ground	1
8	VCC3	+3.3V Power Supply	
9	VCC3	+3.3V Power Supply	
10	SCL	2-Wire Serial Interface Clock. LVTTTL-I	2
11	SDA	2-Wire Serial Interface Data Line. LVTTTL-I/O	2
12	MOD_Abs	Indicates Module is not present. Grounded in the Module. LVTTTL-O	2
13	MOD_NR	Module Not Ready; Indicating Module Operational Fault. Open-collector. LVTTTL-O	2
14	RX_LOS	Loss of Signal indication. Logic 1 indicates loss of Signal. Open-collector. LVTTTL-O	2
15	GND	Module Ground	1
16	GND	Module Ground	1
17	RD-	Receiver Inverted Data Output. CML-O	
18	RD+	Receiver Non-Inverted Data Output. CML-O	
19	GND	Module Ground	1
20	VCC2	+1.8V Power Supply (Not required).	3
21	P_DOWN/RST	Power down; When high, requires the module to limit power consumption to 1.5W or below. 2-Wire serial interface must be functional in the low power mode. LVTTTL-I Reset; The falling edge initiates a complete reset of the module including the 2-wire serial interface, equivalent to a power cycle. LVTTTL-I	
22	VCC2	+1.8V Power Supply (Not required)	3
23	GND	Module Ground	1
24	REFCLK+	Reference Clock (Not required)	
25	REFCLK-	Reference Clock (Not required)	
26	GND	Module Ground	1
27	GND	Module Ground	1
28	TD-	Transmitter Inverted Data Input. CML-I	
29	TD+	Transmitter Non-Inverted Data Input. CML-I	
30	GND	Module Ground	1

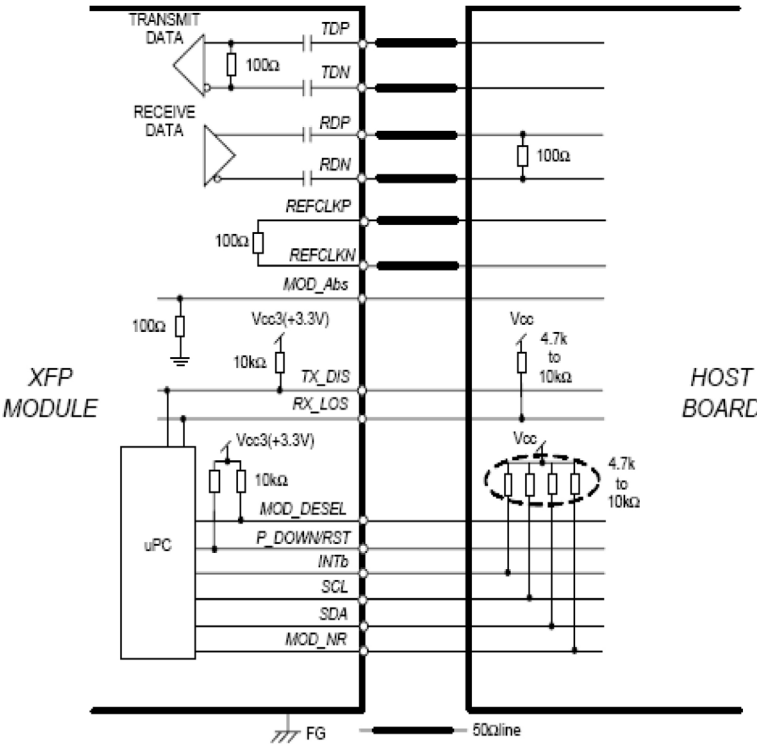
Notes:

1. Module ground pins GND are isolated from the module case and chassis ground within the module.
2. Open collector; should be pulled up with 4.7K-10Kohms to a voltage between 3.15V and 3.6V on the host board.
3. The pins are open within module.



Pin-out of connector Block on Host board

Recommended Circuit Schematic



Mechanical Specifications

Small Form Factor Pluggable (XFP) transceivers are compatible with the dimensions defined by the XFP Multi-Sourcing Agreement (MSA).



EEPROM Information

Management Interface

XFP 2-wire serial interface is specified in the Chapter 4 of the XFP MSA specification. The XFP 2-wire serial interface is used for serial ID, digital diagnostics, and certain control functions. The 2-wire serial interface is mandatory for all XFP modules. The 2-wire serial interface address of the XFP module is 1010000X(A0h). In order to access to multiple modules on the same 2-wire serial bus, the XFP has a MOD_DESEL(module deselect pin). This pin (which is pull high or deselected in the module) must be held low by the host to select of interest and allow communication over 2-wire serial interface. The module must not respond to or accept 2-wire serial bus instructions unless it is selected.

XFP Management Interface

XFP Management interface is specified in the Chapter 5 of the XFP MSA specification. The Figure 1 shows the structure of the memory map. The normal 256 Byte address space is divided into lower and upper blocks of 128 Bytes. The lower block of 128 Byte is always directly available and is used for the diagnostics and control functions that must be accessed repeatedly. Multiple blocks of memories are available in the upper 128 Bytes of the address space. These are individually addressed through a table select Byte which the user enters into a location in the lower address space. The upper address space tables are used for less frequently accessed functions and control space for future standards definition.

EEPROM memory map specific data field description is as below:

